# CLAIMS

1. A composition for electronic device comprising:

(a) a (meth)acrylic compound; (b) a maleimide compound; and

(c) a particle having a functional group having metal scavenging functionality, wherein said maleimide compound is present from 1 to 20% by weight based on the total weight of said composition.

2. The composition according to Claim 1, wherein the functional group having metal scavenging functionality is selected from the group consisting of carboxy group, amine group and imidazole group.

3. The composition according to Claim 1 or 2, wherein the particle is porous polystyrene and/or silica gel having one or more functional groups having metal scavenging functionality.

~~4. The composition according to any one of Claims 1 to 3, further comprising (b) a maleimide compound.~~

~~5~~4. The composition according to ~~Claim 4~~any one of claims 1 to 3, wherein the maleimide compound comprises a bismaleimide.

~~6~~5. The composition according to any one of Claims 1 to ~~5~~4, further comprising a radical initiator.

~~7~~6. The composition according to any one of Claims 1 to ~~6~~5, which is used as an underfill sealant.

~~8~~7. The composition according to any one of Claims 1 to ~~7~~6, which is used in flip chip mounting.

~~9~~8. An electronic device comprising a cured product of the composition according to any one of Claims 1 to ~~8~~7.

~~10~~9. An electronic appliance comprising the electronic device according to Claim ~~9~~8.